
Mechanical standardization of semiconductor devices - Part 6-8: General rules for the preparation of outline drawings of surface mounted semiconductor device package - Design guide for glass sealed ceramic quad flatpack (G-QFP) (IEC 60191-6-8:2001)

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Mechanische Normung von Halbleiterbauelementen -- Teil 6-8: Allgemeine Regeln für die Erstellung von Gehäusezeichnungen von SMD-Halbleitergehäusen - Konstruktionsleitfaden für Glas-Keramik-Quad-Flatpack (G-QFP)

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Normalisation mécanique des dispositifs à semiconducteurs -- Partie 6-8: Règles générales pour la préparation des dessins d'encombrement des dispositifs à semiconducteurs à montage en surface - Guide de conception pour les boîtiers plats quadrangulaires en céramique, scellement verre

Ta slovenski standard je istoveten z: EN 60191-6-8:2001

ICS:

01.100.25	Risbe s področja elektrotehnike in elektronike	Electrical and electronics engineering drawings
31.080.01	Polprevodniški elementi (naprave) na splošno	Semiconductor devices in general
31.240	Mehanske konstrukcije za elektronsko opremo	Mechanical structures for electronic equipment

SIST EN 60191-6-8:2002

en

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EUROPEAN STANDARD

EN 60191-6-8

NORME EUROPÉENNE

EUROPÄISCHE NORM

October 2001

ICS 31.080.01

English version

Mechanical standardization of semiconductor devices
Part 6-8: General rules for the preparation of outline drawings of
surface mounted semiconductor device packages -
Design guide for glass sealed ceramic quad flatpack (G-QFP)
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Normalisation mécanique des dispositifs
à semiconducteurs

Partie 6-8: Règles générales pour
la préparation des dessins

d'encombrement des dispositifs à
semiconducteurs à montage en surface -

Guide de conception pour les boîtiers

plats quadrangulaires en céramique,
scellement verre

(CEI 60191-6-8:2001)

Mechanische Normung von
Halbleiterbauelementen

Teil 6-8: Allgemeine Regeln für
die Erstellung von Gehäusezeichnungen

von SMD-Halbleitergehäusen -

Konstruktionsleitfaden für Glas-Keramik-
Quad-Flatpack (G-QFP)

(IEC 60191-6-8:2001)

[SIST EN 60191-6-8:2002](https://standards.iteh.ai/catalog/standards/sist/85c49bf4-9d13-4d26-b69f-b410576489b0/sist-en-60191-6-8-2002)

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This European Standard was approved by CENELEC on 2001-10-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Malta, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 47D/438/FDIS, future edition 1 of IEC 60191-6-8, prepared by SC 47D, Mechanical standardization of semiconductor devices, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60191-6-8 on 2001-10-01.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2002-07-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2004-10-01

Annexes designated "normative" are part of the body of the standard.
In this standard, annex ZA is normative.
Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60191-6-8:2001 was approved by CENELEC as a European Standard without any modification.

[SIST EN 60191-6-8:2002](https://standards.iteh.ai/catalog/standards/sist/85c49bf4-9d13-4d26-b69f-b410576489b0/sist-en-60191-6-8-2002)
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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

This European Standard incorporates by dated or undated reference, provisions from other publications. These normative references are cited at the appropriate places in the text and the publications are listed hereafter. For dated references, subsequent amendments to or revisions of any of these publications apply to this European Standard only when incorporated in it by amendment or revision. For undated references the latest edition of the publication referred to applies (including amendments).

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60191	Series	Mechanical standardization of semiconductor devices	EN 60191	Series

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INTERNATIONAL STANDARD

IEC 60191-6-8

First edition
2001-08

Mechanical standardization of semiconductor devices –

Part 6-8:

**General rules for the preparation of outline
drawings of surface mounted semiconductor
device packages –**

**Design guide for glass sealed ceramic quad
flatpack (G-QFP)**

<https://standards.iteh.ai/catalog/standards/sist/85c49bf4-9d13-4d26-b69f-b410576489b0/sist-en-60191-6-8-2002>

Normalisation mécanique des dispositifs à semiconducteurs

Partie 6-8:

*Règles générales pour la préparation des dessins
d'encombrement des dispositifs à semiconducteurs
à montage en surface –*

*Guide de conception pour les boîtiers plats quadrangulaires
en céramique, scellement verre*

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –**Part 6-8: General rules for the preparation of outline drawings
of surface mounted semiconductor device packages –
Design guide for glass sealed ceramic quad flatpack (G-QFP)**

FOREWORD

- 1) The IEC (International Electrotechnical Commission) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of the IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, the IEC publishes International Standards. Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. The IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
- 2) The formal decisions or agreements of the IEC on technical matters express, as nearly as possible, an international consensus of opinion on the relevant subjects since each technical committee has representation from all interested National Committees.
- 3) The documents produced have the form of recommendations for international use and are published in the form of standards, technical specifications, technical reports or guides and they are accepted by the National Committees in that sense.
- 4) In order to promote international unification, IEC National Committees undertake to apply IEC International Standards transparently to the maximum extent possible in their national and regional standards. Any divergence between the IEC Standard and the corresponding national or regional standard shall be clearly indicated in the latter.
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- 6) Attention is drawn to the possibility that some of the elements of this International Standard may be the subject of patent rights. The IEC shall not be held responsible for identifying any or all such patent rights.

International Standard IEC 60191-6-8 has been prepared by subcommittee 47D: Mechanical standardization of semiconductor devices, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47D/438/FDIS	47D/456/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 3.

The committee has decided that the contents of this publication will remain unchanged until 2005. At this date, the publication will be

- reconfirmed;
- withdrawn;
- replaced by a revised edition, or
- amended.

A bilingual version of this standard may be issued at a later date.

MECHANICAL STANDARDIZATION OF SEMICONDUCTOR DEVICES –

Part 6-8: General rules for the preparation of outline drawings of surface mounted semiconductor device packages – Design guide for glass sealed ceramic quad flatpack (G-QFP)

1 Scope and object

This part of IEC 60191 provides the common outline drawings and dimensions for all types of structures and composed materials of glass sealed ceramic quad flatpack (hereinafter called G-QFP).

The object of this design guide is to standardize outlines and obtain interchangeability of G-QFP.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 60191. For dated references, subsequent amendments to, or revisions of, any of these publications do not apply. However, parties to agreements based on this part of IEC 60191 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. For undated references, the latest edition of the normative document referred to applies. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 60191 (all parts), *Mechanical standardization of semiconductor devices*
<https://standards.itec.org/catalog/standards/sist/63c496b4-9d13-4d26-b07f-b410576489b0/sist-en-60191-6-8-2002>

3 Definitions

For the purpose of this part of IEC 60191, the following definition, as well as those given in the other parts of this standard, apply.

3.1

G-QFP

glass sealed package with gull-wing formed terminals which are led out in four directions to mount on PCB surface

4 Numbering of the pins

The index area is positioned at the upper left corner of the package body when it is viewed from the seating plane. The terminal that is closest to the index corner is numbered 1, and continued terminals that count in counter-clockwise directions are numbered 2, 3.